

As a below named inventor, I hereby declare that my residence, post office address and citizenship are as stated below next to my name, and I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the INVENTION ENTITLED METHOD OF FABRICATING A

SEMICONDUCTOR LIGHT-EMITTING ELEMENT

the specification of which (CHECK applicable BOX(ES))

- > ☐ is attached hereto.  
-> ☐ was filed on \_\_\_\_\_ as U.S. Application No. 0 / \_\_\_\_\_  
X(ES) -> ☒ was filed as PCT International Application No. PCT/ \_\_\_\_\_ / \_\_\_\_\_ on \_\_\_\_\_  
-> -> and (if applicable to U.S. or PCT application) was amended on \_\_\_\_\_

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above. I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56. I hereby claim foreign priority benefits under 35 U.S.C. 119/365 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate filed by me or my assignee disclosing the subject matter claimed in this application and having a filing date (1) before that of the application on which priority is claimed, or (2) if no priority claimed, before the filing date of this application:

PRIOR FOREIGN APPLICATION(S)

Number	Country	Day/MONTH/Year Filed	Date first Laid-open or Published	Date Patented or Granted	Priority Claimed Yes No
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H11-181897	JAPAN	28/JUNE/1999			XXX
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I hereby claim the benefit under 35 U.S.C. 120/365 of all United States applications listed below and PCT international applications listed above or below and, if this is a continuation-in-part (CIP) application, insofar as the subject matter disclosed and claimed in this application is in addition to that disclosed in such prior applications, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in 37 C.F.R. 1.56 which became available between the filing date of each such prior application and the national or PCT international filing date of this application:

PRIOR U.S. OR PCT APPLICATION(S)

Application No. (series code/serial no.)	Day/MONTH/Year Filed	Status pending, abandoned, patented
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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

And I hereby appoint Cushman Darby & Cushman, L.L.P. 1100 New York Avenue, N.W., Ninth Floor, East Tower Washington, D.C. 20005-3918, telephone number 861-3000 (to whom all communications are to be directed), and the below-named persons (of the same address) individually and collectively my attorneys to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith and with the resulting patent, and I hereby authorize them to act and rely on instructions from and communicate directly with the person/assignee/attorney/firm/ organization who/which first sends/sent this case to them and by whom/which I hereby declare that I have consented after full disclosure to be represented unless/until I instruct Cushman, Darby & Cushman in writing to the contrary.

Paul N. Kokulis	16773	Edward M. Prince	22429	Dale S. Lazar	28872	Michelle N. Lester	32331
Raymond F. Lippitt	17519	Donald B. Deaver	23048	Glenn J. Perry	28458	Jeffrey A. Simenauer	31933
G. Lloyd Knight	17698	David W. Brinkman	20817	Kendrew H. Colton	30368	Robert A. Molan	29834
Carl G. Love	18781	George M. Sirilla	18221	Chris Comuntzis	31097	G. Paul Edgell	24238
Edgar H. Martin	20534	Donald J. Bird	25323	Wallace G. Walter	27843	Lynn E. Eccleston	35861
William K. West, Jr.	22057	W. Warren Taltavull	25647	Lawrence Harbin	27644	Frederick S. Frei	27105
Kevin E. Joyce	20508	Peter W. Gowdey	25872	Paul E. White, Jr.	32011	David A. Jakopin	32995
						Mark G. Paulson	30793

1. INVENTOR'S SIGNATURE: Toshiya Uemura Date June 20, 2000  
Inventor's Name (typed) Toshiya UEMURA JAPAN  
Residence (City) Aichi (State/Foreign Country) JAPAN  
Post Office Address (Include Zip Code) 2-10-405, Kanehira-cho, Tsushima-shi, Aichi-ken, 496-0812, JAPAN

2. INVENTOR'S SIGNATURE: Takahide Oshio Date June 20, 2000  
Inventor's Name (typed) Takahide OSHIO JAPAN  
Residence (City) Aichi (State/Foreign Country) JAPAN  
Post Office Address (Include Zip Code) 953, Ono, Azai-cho, Ichinomiya-shi, Aichi-ken, 491-0143, JAPAN

3. INVENTOR'S SIGNATURE: \_\_\_\_\_ Date \_\_\_\_\_  
Inventor's Name (typed) \_\_\_\_\_  
Residence (City) \_\_\_\_\_ (State/Foreign Country) \_\_\_\_\_  
Post Office Address (Include Zip Code) \_\_\_\_\_

(FOR ADDITIONAL INVENTORS, check box ☐ and attach sheet (CDC-116.2) for same information for each re signature, name, date, citizenship, residence and address.)